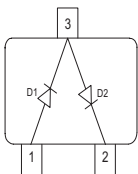


Silicon PIN Diode Array

- Surge protection device
- Designed for surge overvoltage clamping in antiparallel connection
- Pb-free (RoHS compliant) package


BAR66


Type	Package	Configuration	L_S (nH)	Marking
BAR66	SOT23	series	1.8	PMs

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	150	V
Forward current	I_F	200	mA
Total power dissipation $T_s \leq 25^\circ\text{C}$	P_{tot}	250	mW
ESD contact discharge ¹⁾	V_{ESD}	25	kV
Peak pulse current ($t_p = 8 / 20 \mu\text{s}$) ²⁾	I_{pp}	12	A
Junction temperature	T_j	150	°C
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ³⁾ , BAR 66	R_{thJS}	≤ 290	K/W

¹⁾ V_{ESD} according to IEC61000-4-2, only valid if pin 1 and pin 2 are connected

²⁾ I_{pp} according to IEC61000-4-5, only valid if pin 1 and pin 2 are connected

³⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

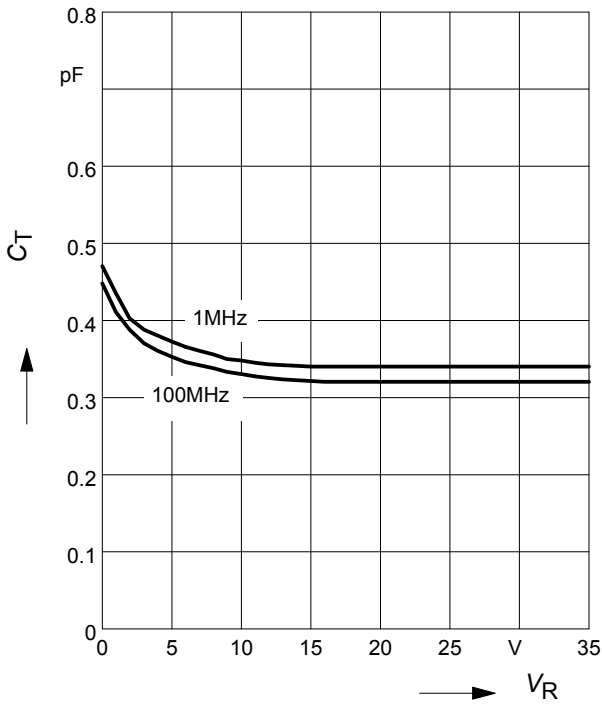
Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Breakdown voltage $I_{(BR)} = 5 \mu\text{A}$	$V_{(BR)}$	150	-	-	V
Reverse current $V_R = 100 \text{ V}$	I_R	-	-	20	nA
Forward voltage $I_F = 50 \text{ mA}$	V_F	-	0.95	1.2	V
Clamping voltage $V_{ESD} = \pm 15 \text{ kV (contact)}^1$ $I_{PP} = 12 \text{ A}, t_p = 8/20 \mu\text{s}^2$	V_{CL}	-	tbd 7	-	
AC Characteristics					
Diode capacitance $V_R = 35 \text{ V}, f = 1 \text{ MHz}$ $V_R = 0 \text{ V}, f = 100 \text{ MHz}$	C_T	-	0.4 0.35	0.6 0.9	pF
Zero bias conductance $V_R = 0 \text{ V}, f = 1 \text{ GHz}$	g_P	-	220	-	μS
Forward resistance $I_F = 5 \text{ mA}, f = 100 \text{ MHz}$	r_f	-	1.5	1.8	Ω
Charge carrier life time $I_F = 10 \text{ mA}, I_R = 6 \text{ mA}$, measured at $I_R = 3 \text{ mA}$, $R_L = 100 \Omega$	τ_{rr}	-	0.7	-	μs

¹ V_{ESD} according to IEC61000-4-2, only valid if pin 1 and pin 2 are connected

² I_{pp} according to IEC61000-4-5, only valid if pin 1 and pin 2 are connected

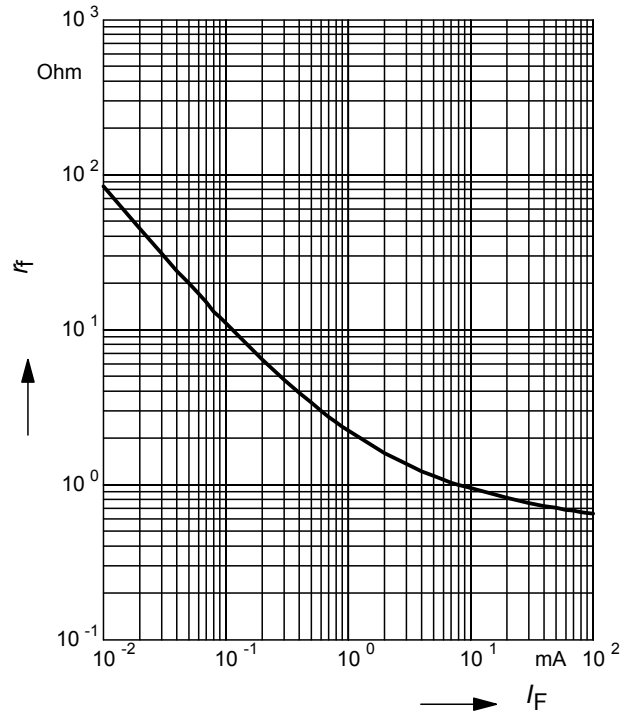
Diode capacitance $C_T = f(V_R)$

$f =$ Parameter



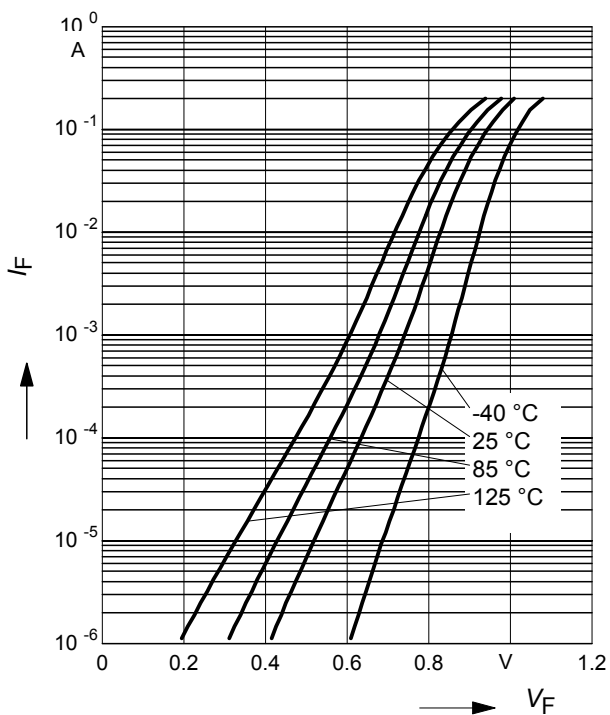
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$



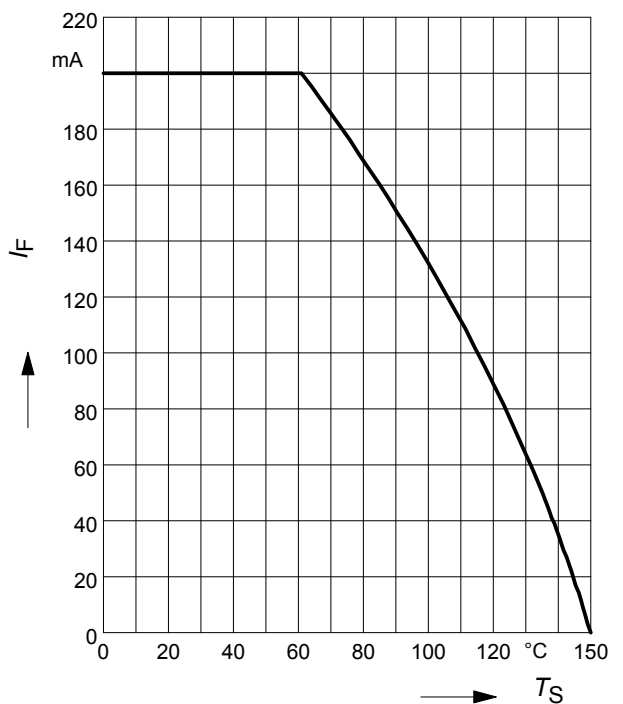
Forward current $I_F = f(V_F)$

$T_A =$ Parameter



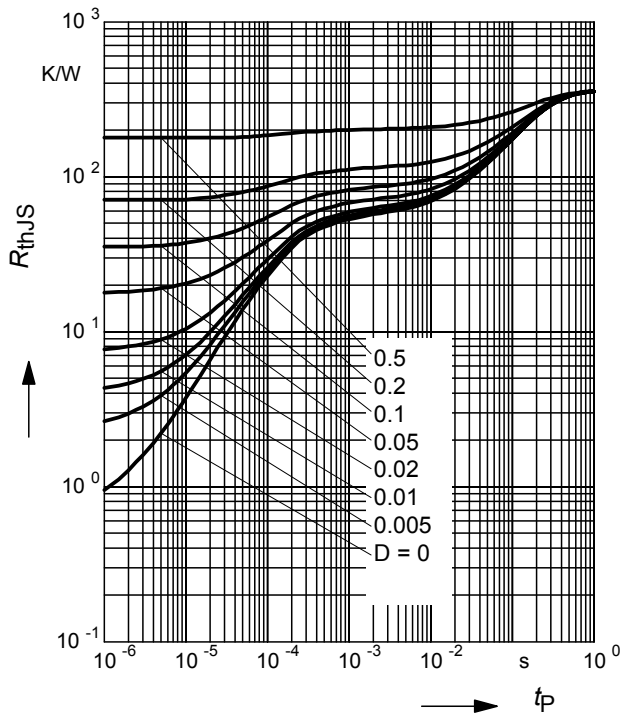
Forward current $I_F = f(T_S)$

BAR66



Permissible Puls Load $R_{thJS} = f(t_p)$

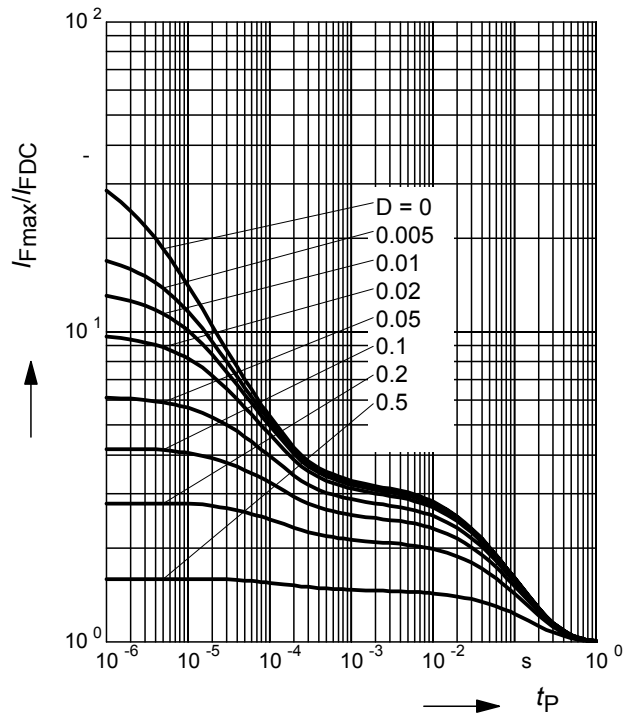
BAR66



Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$

BAR66

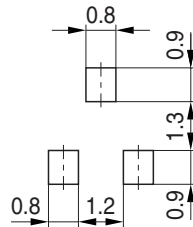


Package Outline



1) Lead width can be 0.6 max. in dambar area

Foot Print

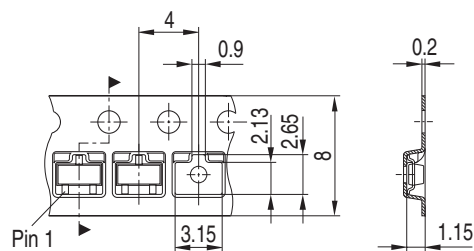


Marking Layout (Example)



Standard Packing

Reel \varnothing 180 mm = 3.000 Pieces/Reel
 Reel \varnothing 330 mm = 10.000 Pieces/Reel



Edition 2009-11-16

**Published by
Infineon Technologies AG
81726 Munich, Germany**

**© 2009 Infineon Technologies AG
All Rights Reserved.**

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office ([<www.infineon.com>](http://www.infineon.com)).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Infineon:](#)

[BAR66E6327HTSA1](#)